

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

MATERIAL:

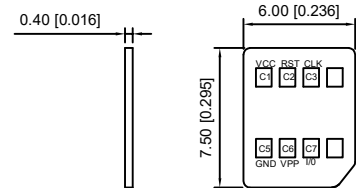
Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature : 260°C ±5°



MICRO SIM CARD

■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

ECN BO.		DESCRIPTION.		DATE.	REV.	SCALE: 3:1
DESIGNED	CHECKED	APPROVAL	DRAWING NUMBER		SCALT: 1/2	
Mikey	Tom	Jerry	PART NAME	SIM-114	UNLESS OTHERWISE SPECIFIED,TOLERANCE:	X. ±0.25 X.x ±0.20 X.xx ±0.15 ANGULAIR ±3
			MODEL NAME	SIM-114		
			3RD ANGLE PROJ	HanElectricity Co.,LTD		FILE.NO.

瀚源